

## 30V P-Channel Enhancement Mode MOSFET

### GENERAL DESCRIPTION

The **ME9435** is the P-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology.

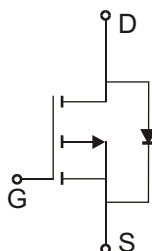
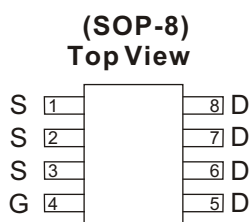
This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and low in-line power loss that are needed in a very small outline surface mount package.

### FEATURES

1. -30V/-5.3A,  $R_{DS(ON)}=60m\Omega@V_{GS}=-10V$
2. -30V/-4.2A,  $R_{DS(ON)}=100m\Omega@V_{GS}=-4.5V$

### PIN CONFIGURATION



Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)			
Parameter	Symbol	Limits	Units
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	-5.3	A
Pulsed Drain Current <sup>1)</sup>	I <sub>DM</sub>	-20	A
Maximum Power Dissipation	P <sub>D</sub>	TA=25°C	W
		TA=70°C	
Operating Junction Temperature	T <sub>J</sub>	-55 to 150	°C
Junction-to-Case Thermal Resistance	R <sub>θJC</sub>	30	°C/W
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>	R <sub>θJA</sub>	50	°C/W

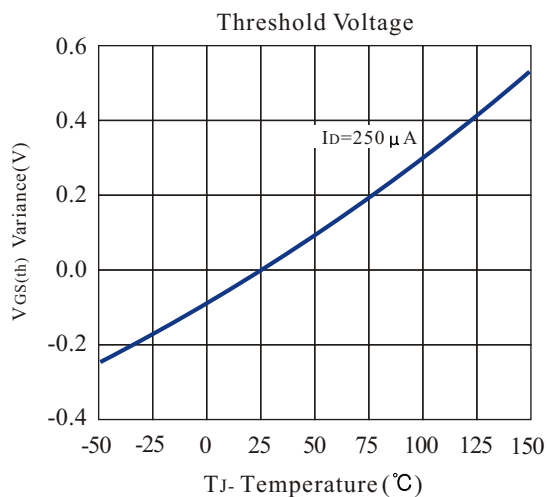
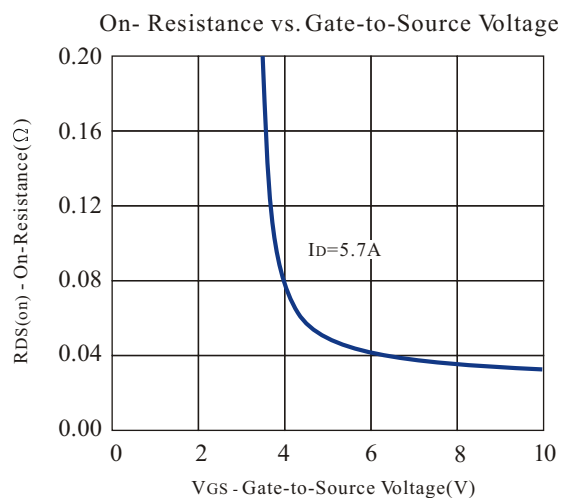
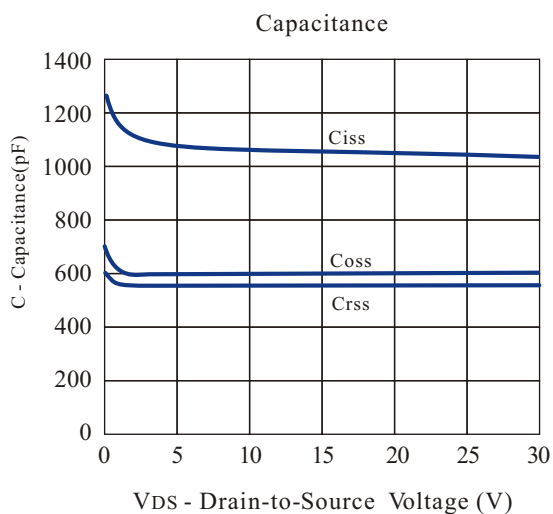
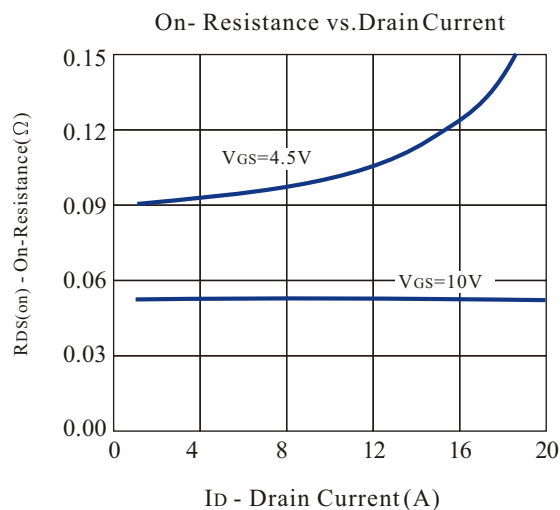
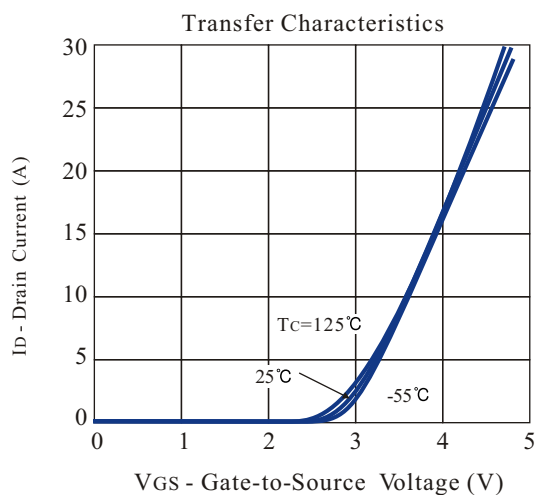
Notes: 1. Maximum DC current limited by the package  
2. 1-in<sup>2</sup> 2oz Cu PCB board

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### Electrical Characteristics (T<sub>J</sub> = 25°C Unless Specified)

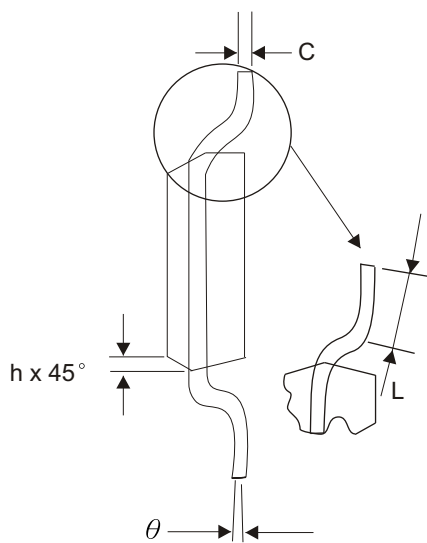
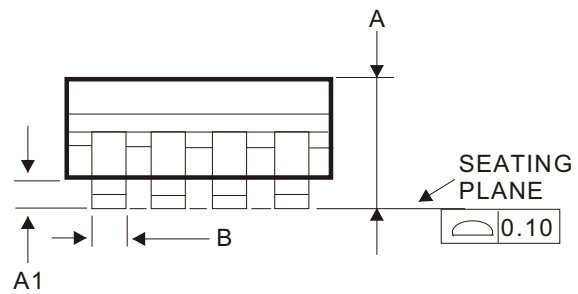
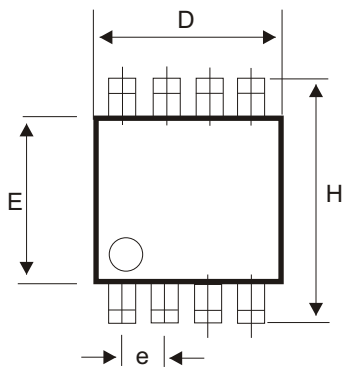
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250 μA	-30			V
R <sub>DS(ON)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> = -10V, I <sub>D</sub> = -5.3A		0.055	0.06	Ω
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4.2A		0.09	0.1	
V <sub>GS(th)</sub>	Gate-Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1.0	-2.2	-3.0	V
I <sub>GSS</sub>	Gate-Body Leakage	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V			-1	μA
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -15V, I <sub>D</sub> = -5.3A	4	7		S
<b>DYNAMIC</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -15V, I <sub>D</sub> = -5.3A, V <sub>GS</sub> = -10V		9.52		nC
Q <sub>gs</sub>	Gate-Source Charge			3.43		
Q <sub>gd</sub>	Gate-Drain Charge			1.71		
t <sub>D(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -15V, R <sub>L</sub> = 15 Ω I <sub>D</sub> = -1A, V <sub>GEN</sub> = -10V R <sub>G</sub> = 6 Ω		10.8		ns
t <sub>r</sub>	Turn-On Rise Time			2.33		
t <sub>D(off)</sub>	Turn-Off Delay Time			22.53		
t <sub>f</sub>	Turn-Off Fall Time			3.87		
<b>SOURCE-DRAIN DIODE</b>						
I <sub>S</sub>	Max.Diode Forward Current				-1.9	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> = -5.3A, V <sub>GS</sub> = 0V			-1.3	V

### Typical Characteristics (T<sub>J</sub> = 25°C Noted)



Physical Dimensions inches(millimeters) unless otherwise noted

### SOP-8



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
$\theta$	0°	7°